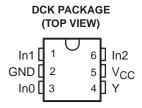
- Controlled Baseline
 - One Assembly/Test Site, One Fabrication Site
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree[†]
- Supports 5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 6.3 ns at 3.3 V
- Low Power Consumption, 10-μA Max I_{CC}

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- ±24-mA Output Drive at 3.3 V
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- Choose From Nine Specific Logic Functions



description/ordering information

This configurable multiple-function gate is designed for 1.65-V to 5.5-V V_{CC} operation.

The SN74LVC1G97 features configurable multiple functions. The output state is determined by eight patterns of 3-bit input. The user can choose the logic functions MUX, AND, OR, NAND, NOR, inverter, and noninverter. All inputs can be connected to V_{CC} or GND.

This device functions as an independent gate, but because of Schmitt action, it may have different input threshold levels for positive-going (V_{T+}) and negative-going (V_{T-}) signals.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

TA	PACKAGE [‡]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SOT (SC-70) – DCK	Tape and reel	SN74LVC1G97IDCKREP	CSR

[‡] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



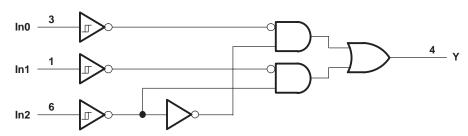
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FUNCTION TABLE

	INPUTS	OUTPUT	
ln2	ln1	In0	Υ
L	L	L	L
L	L	Н	L
L	Н	L	Н
L	Н	Н	Н
Н	L	L	L
Н	L	Н	Н
Н	Н	L	L
Н	Н	Н	Н

logic diagram (positive logic)

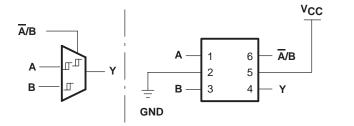


FUNCTION SELECTION TABLE

LOGIC FUNCTION	FIGURE NO.
2-to-1 data selector	1
2-input AND gate	2
2-input OR gate with one inverted input	3
2-input NAND gate with one inverted input	3
2-input AND gate with one inverted input	4
2-input NOR gate with one inverted input	4
2-input OR gate	5
Inverter	6
Noninverted buffer	7

VCC

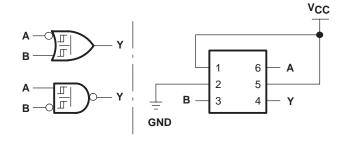
logic configurations



VCC 5 亍 2 3 4 **GND**

Figure 1. 2-to-1 Data Selector

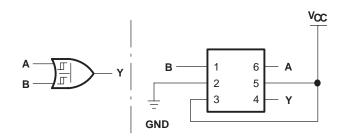
Figure 2. 2-Input AND Gate



2 5 4 GND

Figure 3. 2-Input OR Gate With One Inverted Input
2-Input NAND Gate With One Inverted Input

Figure 4. 2-Input AND Gate With One **Inverted Input** 2-Input NOR Gate With One Inverted Input



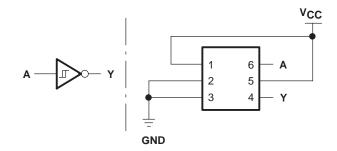


Figure 5. 2-Input OR Gate

Figure 6. Inverter

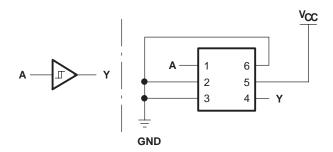


Figure 7. Noninverted Buffer



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 6.5 V
Input voltage range, V _I (see Note 1)	–0.5 V to 6.5 V
Voltage range applied to any output in the high-impedance or power-off state, VO	
(see Note 1)	–0.5 V to 6.5 V
Voltage range applied to any output in the high or low state, VO	
(see Notes 1 and 2)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, $I_{ K }(V_{ I } < 0)$	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, IO	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ _{JA} (see Note 3)	259°C/W
Storage temperature range, T _{stg}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The value of V_{CC} is provided in the recommended operating conditions table.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
.,	0 1 1	Operating	1.65	5.5	.,
VCC	Supply voltage	Data retention only	1.5		V
VI	Input voltage	·	0	5.5	V
Vo	Output voltage		0	VCC	V
		V _{CC} = 1.65 V		-4	
		V _{CC} = 2.3 V		-8	
lOH	IOH High-level output current	У ОУ	-16		mA
		V _{CC} = 3 V		-24	
		V _{CC} = 4.5 V		-32	
		V _{CC} = 1.65 V		4	
		V _{CC} = 2.3 V		8	
loL	Low-level output current	V 0V	16		mA
		VCC = 3 V	24		
		V _{CC} = 4.5 V		32	
TA	Operating free-air temperature		-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CO	NDITIONS	VCC	MIN	TYPT MAX	UNIT
			1.65 V	0.79	1.16	
V _{T+}			2.3 V	1.11	1.56	
Positive-going input threshold			3 V	1.5	1.87	V
voltage			4.5 V	2.16	2.74	
			5.5 V	2.61	3.33	
			1.65 V	0.35	0.62	
V _T _			2.3 V	0.58	0.87	
Negative-going input threshold			3 V	0.84	1.19	V
voltage			4.5 V	1.41	1.9	
			5.5 V	1.87	2.29	
			1.65 V	0.3	0.62	
ΔVT			2.3 V	0.4	0.8	
Hysteresis			3 V	0.53	0.87	V
$(V_{T+} - V_{T-})$			4.5 V	0.71	1.04	
			5.5 V	0.71	1.11	
	I _{OH} = -100 μA		1.65 V to 5.5 V	V _{CC} – 0.1		
	I _{OH} = -4 mA		1.65 V	1.2		
V	IOH = -8 mA		2.3 V	1.9		V
VOH	I _{OH} = −16 mA		3 V	2.4		V
	I _{OH} = -24 mA		3 V	2.3		
	I _{OH} = −32 mA		4.5 V	3.8		
	I _{OL} = 100 μA		1.65 V to 5.5 V		0.1	
	I _{OL} = 4 mA		1.65 V		0.45	
	I _{OL} = 8 mA		2.3 V		0.3	
VOL	I _{OL} = 16 mA		0.1/		0.4	V
	I _{OL} = 24 mA		3 V		0.55	
	I _{OL} = 32 mA		4.5 V		0.55	
II	V _I = 5.5 V or GND		0 to 5.5 V		±5	μΑ
l _{off}	V _I or V _O = 5.5 V		0		±10	μΑ
Icc	V _I = 5.5 V or GND,	I _O = 0	1.65 V to 5.5 V		10	μΑ
ΔlCC	One input at V _{CC} – 0.6 V,	Other inputs at V _{CC} or GND	3 V to 5.5 V		500	μΑ
Ci	V _I = V _{CC} or GND		3.3 V		3.5	pF

 $[\]overline{\dagger}$ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

SN74LVC1G97-EP CONFIGURABLE MULTIPLE-FUNCTION GATE

SCES461B – JUNE 2003 – REVISED FEBRUARY 2005

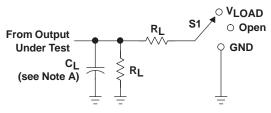
switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 8)

PARAMETER	FROM	TO (OUTPUT)	V _{CC} = ± 0.1		V _{CC} =		V _{CC} =		V _{CC} =		UNIT
	(INPUT)		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
^t pd	Any In	Y	3.2	14.4	2	8.3	1.5	6.3	1.1	5.1	ns

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		TEST	V _{CC} = 1.8 V	$V_{CC} = 2.5 V$	$V_{CC} = 3.3 \text{ V}$	$V_{CC} = 5 V$	LINUT
	PARAMETER		TYP	TYP	TYP	TYP	UNIT
C _{pd}	Power dissipation capacitance	f = 10 MHz	22	23	23	26	pF

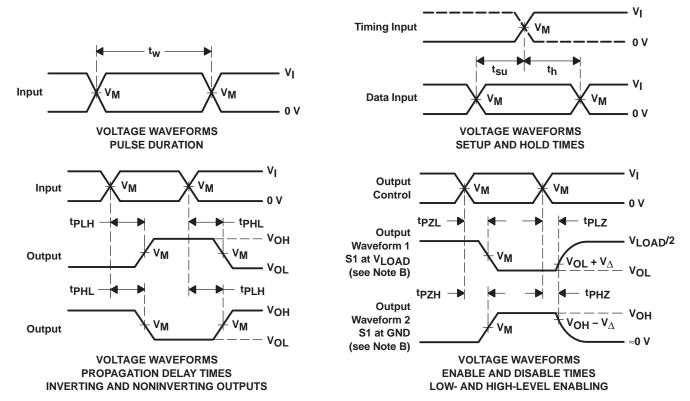
PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	VLOAD
tPHZ/tPZH	GND

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.,	INF	PUTS	.,	.,			.,
VCC	VI	t _r /t _f	VM	VLOAD	CL	R_L	$v_{\!\scriptscriptstyle\Delta}$
1.8 V \pm 0.15 V	VCC	≤2 ns	V _{CC} /2	2×VCC	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	VCC	≤2 ns	V _{CC} /2	2×VCC	30 pF	500 Ω	0.15 V
3.3 V \pm 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
5 V \pm 0.5 V	VCC	≤2.5 ns	V _{CC} /2	2×V _{CC}	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \Omega$.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 8. Load Circuit and Voltage Waveforms







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins F	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LVC1G97IDCKREP	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/03642-01XE	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74LVC1G97-EP:

Catalog: SN74LVC1G97

Automotive: SN74LVC1G97-Q1

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects



TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC1G97IDCKREP	SC70	DCK	6	3000	180.0	9.2	2.24	2.34	1.22	4.0	8.0	Q3





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC1G97IDCKREP	SC70	DCK	6	3000	202.0	201.0	28.0

DCK (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-203 variation AB.



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